## Abstract

A method for separating a comprehensive substrate (3) into a first substrate (13) and a second substrate (23), wherein the first substrate (13) and/or the second substrate (23) is intended to be an element of an electronic component, comprising

- providing the comprehensive substrate (3) comprising the first substrate (13) and the second substrate (23), wherein the first substrate (13) and the second substrate (23) are bonded with each other along a bonding interface via a created bond, preferably via a bond created by a fusion bond, and
- separating the comprehensive substrate (3) into the first substrate (13) and the second substrate (23) along the bonding interface,

wherein an agent for chemical processing and preferably a non-chemical mean are used for separating the comprehensive substrate (3) into the first substrate (13) and the second substrate (23).

[Fig. 1]